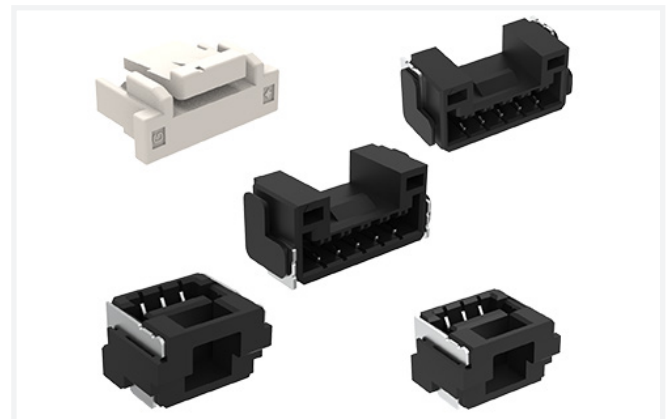


AgilLink™ 1.25mm Wire-to-Board (G880 Series)

CUSTOMIZABLE SHROUDED WIRE-TO-BOARD HEADER

AgilLink™ 1.25mm Wire-to-Board is the most common solution for transferring power and signal. This series can carry a maximum current rating of 1A. Amphenol offers a comprehensive range of these headers including V/T DIP, V/T SMT, R/A DIP, R/A SMT to meet various customer requirements. It comes in customizable for pin length, latch or location post, which makes it an ideal choice for several applications and specific designs.

- Save Space with 1.25mm pitch
- Accommodates wire range up to AWG#26~34
- Latch or post option
- Supports PiP process
- Easy pin insertion and high retention force onto PCB



TARGET MARKETS



FEATURES

- 1.5mm pitch Wire to Board
- Various mounting options including vertical DIP, right angle DIP, vertical SMT and right angle SMT
- High temperature thermoplastic material
- Tape and reel packaging option
- Latch design
- Mates with Header WTB G880, G878 H/C & G884H/C
- RoHS compliance and halogen-free

BENEFITS

- Save device space
- Ease in choosing board mating configurations
- Re-flow compatible
- Supports PiP process
- Ease for Mating and unmating
- Mutually compatible for wire-to-board
- Meets environmental, health and safety requirements

TECHNICAL INFORMATION

MATERIAL

- Housing: High temperature thermoplastic, UL94V-0
- Contact: Copper Alloy, selective Gold or Tin plating on contact area, Gold flash or Tin plating on solder tail and Nickel under-plated overall

MECHANICAL PERFORMANCE

- Contact Retention Force: Base on individual P/N
- Durability: 30 cycles
- Insertion Force: Base on individual P/N
- Withdrawal Force: Base on individual P/N
- Vibration: 1μs max., EIA 364-28
- Mechanical Shock: 1μs max., EIA 364-27

ELECTRICAL PERFORMANCE

- Current Rating: 1A AC/DC
- Voltage Rating: 50VAC/VDC
- Temperature: -40°C to +85°C
- Contact Resistance: 20mΩ max.
- Insulation Resistance: 100MΩ min.

SPECIFICATIONS

- Amphenol Product Specification: GS-880

PACKAGING

- Tape and reel
- Bag

ENVIRONMENTAL

- Thermal Shock: a) -55°C ~ 30 minute. b) +85°C ~ 30 minute, 10 cycles, EIA 364-32
- Humidity: 60°C, 90~95%RH, 240 hours, EIA 364-31
- Heat Resistance : 85°C, 96 hours, EIA 364-17
- Cold Resistance: -40°C, 96 hours, EIA 364-17
- Solderability: 95% min. solder coverage, EIA 364-52
- Resistance to Soldering Heat: Peak Temperature: 260°C max., 10 seconds max.

TARGET MARKETS/APPLICATIONS



Communications



Consumer



Server
Storage



Industrial & Instrumentation



Medical

PART NUMBERS

Part Numbers	Description	3D	2D
G880031111C1HR	Wire-to-Board 1.25mm Pitch, V/T SMT, 1x3PIN, MATTE TIN, NY6T, COLOR-BLACK, T&R, Halogen-free	G880031111C1HR	G880XX1XXXC1HR
G880032111C1HR	Wire-to-Board 1.25mm Pitch, R/A SMT, 1x3Pin, Matte Tin, NY6T, Color-Black, T&R, Halogen-free	G880032111C1HR	G880XX2XXXC1HR
G88005113T3HR	Protect Header 1.25mm Pitch STR SMT, 1x5Pin, Matte Tin, NY9T, Latch Type, Color-Black, W/MYLAR, Halogen-free	G88005113T3HR	G880XX1X3XT3HR
G880052111T5HR	Protect Header 1.25mm Pitch R/A SMT, 1x5Pin, Matte Tin, NY9T, Latch Type, Color-Black, W/MYLAR, Halogen-free	G880052111T5HR	G880XX2X1XT5HR
G884H051T3HR	G884 Series, 1.25mm Pitch, Cable Side Housing, 1x5Pin, NY66, Color-White, Halogen-free	G884H051T3HR	G884HXXXT3HR

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